

Tin 100 μ inches at solder tail, See ordering information for contact Area plating (comply to sony SS-00259)

Shell : SUS 304. t=0.15 mm (comply to sony SS-00259)

Within the 0.3 mm high above the shell, It's the function area and please don't do any design for mechanism

This product applies to the mechanical specification version 1.0 of Scandisk TransFlash memory module

Operating temperature : -25°C to +85°C

Storage temperature range : -40°C to +85°C

T-Flash

Pin	Name
1	DAT2
2	CD / DAT3
3	CMD
4	VDD
5	CLK
6	VSS2
7	DAT0
8	DAT1

Part Number Table

Description	Part Number
Connector, Micro SD, Memory Card	TFCMF-20801B0T0-UTE

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